MANUFACTURING APPARATUS AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

Abstract

A manufacturing apparatus (10) of a semiconductor device includes: a wafer holding device (12) which holds one or more chips (100) adhesively held on a surface of a dicing tape (120) together with the dicing tape (120); a pickup head (14) which picks up a target chip (100); an energy irradiation device (16) which irradiates energy from a back side of the dicing tape (120) toward the target chip (100) to reduce adhesive force of the dicing tape (120); a temperature sensor (44) which detects a temperature in an irradiation area of the energy; and a controller (22). The controller (22) controls drive of the energy irradiation device (16) based on the detected temperature by the temperature sensor (44).

Fig. 1